

## **IN THE CLAIMS:**

The listing of claims replaces all prior versions, and listings, of claims in the application.

1. (Currently amended) A retainer for printed circuit board assemblies, comprising:  
a heat-shrinkable member disposed within the printed circuit board assemblies, said heat-shrinkable member being configured to receive a coupling member extending from a component; and  
a retaining member, said retaining member being coupled with said heat-shrinkable member.

2. (Original) The retainer of Claim 1, wherein said component is assembled on a printed circuit board.

3. (Original) The retainer of Claim 2, wherein said printed circuit board forms an opening, said heat-shrinkable member being configured to receive said coupling member via said opening.

4. (Original) The retainer of Claim 3, wherein said coupling member is configured to be received within said opening.

5. (Original) The retainer of Claim 3, wherein said heat-shrinkable member is configured to be received within said opening.

6. (Original) The retainer of Claim 2, wherein said coupling member is coupled with said component before said component is assembled on said printed circuit board.

7. (Currently amended) ~~The retainer of Claim 2,~~ A retainer for printed circuit board assemblies, comprising:  
a heat-shrinkable member, said heat-shrinkable member being configured to receive a coupling member extending from a component; and  
a retaining member, said retaining member being coupled with said heat-shrinkable member, wherein said component is assembled on a printed circuit board, and wherein said

component is assembled on one side of said printed circuit board, and said retaining member is substantially adjacent to an opposite side of said printed circuit board.

8. (Currently amended) ~~The retainer of Claim 2,~~ A retainer for printed circuit board assemblies, comprising:

a heat-shrinkable member, said heat-shrinkable member being configured to receive a coupling member extending from a component; and  
a retaining member, said retaining member being coupled with said heat-shrinkable member, wherein said component is assembled on a printed circuit board, and wherein said printed circuit board is disposed substantially between said retaining member and said component.

9. (Original) The retainer of Claim 2, wherein said heat-shrinkable member is sufficiently laterally flexible to permit a surface tension of liquefied solder to substantially guide a substantially horizontal alignment of said component during assembly.

10. (Original) The retainer of Claim 1, wherein said heat-shrinkable member is configured to activate at a temperature that is less than or substantially equal to a typical solder reflow temperature.

11. (Currently amended) ~~The retainer of Claim 1,~~ A retainer for printed circuit board assemblies, comprising:

a heat-shrinkable member, said heat-shrinkable member being configured to receive a coupling member extending from a component; and  
a retaining member, said retaining member being coupled with said heat-shrinkable member, wherein said heat-shrinkable member is configured to resist decomposition at a temperature that is greater than a typical solder reflow temperature.

12. (Original) The retainer of Claim 1, wherein said heat-shrinkable member includes a channel to receive said coupling member.

13. (Original) The retainer of Claim 12, wherein said heat-shrinkable member comprises heat-shrinkable tubing.

14. (Original) The retainer of Claim 1, wherein said heat-shrinkable member is configured to shrinkably-engage said coupling member when exposed to a temperature that is less than or substantially equal to a typical solder reflow temperature.

15. (Original) The retainer of Claim 1, wherein said retaining member is formed from a heat-resistant material.

16. (Currently amended) ~~The retainer of Claim 15,~~ A retainer for printed circuit board assemblies, comprising:

a heat-shrinkable member, said heat-shrinkable member being configured to receive a coupling member extending from a component; and  
a retaining member, said retaining member being coupled with said heat-shrinkable member, wherein said retaining member is formed from a heat-resistant material, and  
wherein said heat-resistant material is configured to remain functionally stable at a temperature that is greater than or substantially equal to a typical solder reflow temperature.

17. (Original) The retainer of Claim 1, wherein said retaining member includes an extension, said retaining member being coupled with said heat-shrinkable member via said extension.

18. (Currently amended) ~~The retainer of Claim 1,~~ A retainer for printed circuit board assemblies, comprising:

a heat-shrinkable member, said heat-shrinkable member being configured to receive a coupling member extending from a component; and  
a retaining member, said retaining member being coupled with said heat-shrinkable member, wherein said retaining member forms an aperture, said heat-shrinkable member being disposed substantially within said aperture.

19. (Currently amended) A retainer for printed circuit board assemblies, comprising:

at least one heat-shrinkable member disposed within the printed circuit board assemblies, said at least one heat-shrinkable member each being configured to receive a coupling member extending from a component assembled on a printed circuit board via an opening formed in said printed circuit board; and

a retaining member, said retaining member being coupled with each of said plurality of heat-shrinkable members.

20. (Original) The retainer of Claim 19, wherein a second coupling member extends from said component, and at least one of said at least one heat-shrinkable member is configured to receive said second coupling member via a second opening formed in said printed circuit board.

21. (Original) The retainer of Claim 19, wherein a second component is assembled on said printed circuit board, and at least one of said at least one heat-shrinkable member is configured to receive a coupling member extending from said second component via a second opening formed in said printed circuit board.

22. (Original) The retainer of Claim 19, wherein at least one of said at least one heat-shrinkable member is configured to shrinkably engage at least one of said at least one coupling member when exposed to a temperature that is less than or substantially equal to a typical solder reflow temperature.

23. (Currently amended) A retainer for printed circuit board assemblies, comprising:  
a retaining member, said retaining member having at least one coupling member, said at least one coupling member each extending from said retaining member; and  
a heat-shrinkable member, said heat-shrinkable member being coupled with a component assembled on a printed circuit board and being configured to receive at least one of said at least one coupling member ~~via~~ within an opening formed in said printed circuit board.

24. (Original) The retainer of Claim 23, wherein a second heat-shrinkable member is coupled with said component, said second heat-shrinkable member being configured to receive at least one of said at least one coupling member via a second opening formed in said printed circuit board.

25. (Original) The retainer of Claim 23, wherein a second component is assembled on said printed circuit board and is coupled with a heat-shrinkable member, said heat-

shrinkable member of said second component being configured to receive at least one of said at least one coupling member via a second opening formed in said printed circuit board.

26. (Original) The retainer of Claim 23, wherein said heat-shrinkable member is configured to shrinkably engage at least one of said at least one coupling member when exposed to a temperature that is less than or substantially equal to a typical solder reflow temperature.

27. – 42. (Canceled)